

DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

"OPTIMIZATION OF IN-MOLD COATING INJECTION MOLDED THERMOPLASTIC SUBSTRATES"

the specification of	of which				
	is attached heret was filed on and was amende	as App	plication Serial No (if applicable).		
I hereby state that to above.	I have reviewe	d and understand th	ne contents of the above-identified specification, including the claims, as	amended by any amer	idment referred
I acknowledge the §1,56(a).	e duty to disclos	se information which	ch is material to the examination of this application in accordance with	Γitle 37, Code of Feder	al Regulations,
have also identifie	d below any for	enefits under title 3 reign application for	5, United States Code, §119 of any foreign application(s) for patent or r patent or inventor's certificate having a filing date before that of the appropriate the state of the second sta	inventor's certificate li dication on which prior	sted below and rity is claimed:
Proof Foreign App	olication(s)			Priority	Claimed
(Number)		(Country)	(Day/Month/Year Filed)	Yes	No
(Number)		(Country)	(Day/Month/Year Filed)	Yes	No
(Number)	-	(Country)	(Day/Month/Year Filed)	Yes	No
claims of this app	lication is not di duty to disclos	sclosed in the prior e material informati	tes Code, §120 of any United States application(s) listed below and, inso United States application in the manner provided by the first paragraph ion as defined in Title 37, Code of Federal Regulations, §1.56(a) which all filing date of this application:	of Title 35, United Stat	tes Code, §112,
09/614,953 (Application Seria	ol No.)	07/12/00 Filing Date)	Pending (Status: patented, pending, abandoned)		
(Application Seria		Filing Date)	(Status: patented, pending, abandoned)		
herewith: Robert	F. Rywalski, F	leg. No. 25,125; D	ent(s) to prosecute this application and to transact all business in the Pa baniel J. Hudak, Reg. No. 25,879; Laura F. Shunk, Reg. No. 31,423; 1 rpak, Reg. No. 42,192; Cheryl L. Farine, Reg. No. 36,796 and Daniel	Frank C. Rote, Jr., Re	g. No. 20,395;
Address all teleph	one calls to: Ro	bert F. Rywalski te	elephone No. (330) 869-4471		
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application of any patent issued thereon.





DECLARATION FOR PATENT APPLICATION, page 2

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THIRD Inventor(s) Signature Inventor(s) Typed Name: Lohn A. Thompson Residence (City): Wooster Post Office Address: _1578 Woodcrest Drive, Wooster, Ohio 44691	Date 10/09/0/ Citizenship: LISA State/Foreign Country: Ohio